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### 495885 -- Patent Information

Published Serial No.	<b>495885</b>									
Title	<b>Method and apparatus for processing a microelectronic workpiece at an elevated temperature</b>									
Patent type	<b>B</b>									
Date of Grant	<b>2002/7/21</b>									
Application Number	<b>090102866</b>									
Filing Date	<b>2001/2/9</b>									
IPC	<b>H01L21/324</b>									
Inventor	<b>WEAVER, ROBERT A.(US)</b> <b>WILSON, GREGORY J.(US)</b> <b>MCHUGH, PAUL R.(US)</b> <b>ZILA, VLADIMIR(CA)</b>									
Priority	<table border="1"> <thead> <tr> <th>Country</th> <th>Application Number</th> <th>Priority Date</th> </tr> </thead> <tbody> <tr> <td></td> <td><b>US20000501002</b></td> <td><b>2000/02/09</b></td> </tr> <tr> <td></td> <td><b>US20000733608</b></td> <td><b>2000/12/08</b></td> </tr> </tbody> </table>	Country	Application Number	Priority Date		<b>US20000501002</b>	<b>2000/02/09</b>		<b>US20000733608</b>	<b>2000/12/08</b>
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Abstract	An apparatus and method for processing a microelectronic workpiece at an elevated temperature. In one embodiment, the apparatus includes a workpiece support positioned to									

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engage and support the microelectronic workpiece during operation. The apparatus can further include a heat source having a solid engaging surface positioned to engage a surface of the microelectronic workpiece with at least one of the heat source and the workpiece support being movable relative to the other between a first position with the microelectronic workpiece contacting the engaging surface of the heat source and a second position with the microelectronic workpiece spaced apart from the engaging surface. The heat source is sized to transfer heat to the microelectronic workpiece at a rate sufficient to thermally process a selected material of the microelectronic workpiece when the microelectronic workpiece is engaged with the heat source. A heat sink can be positioned at least proximate to the heat source to cool both the heat source and the microelectronic workpiece.

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